

THIS INFORMATION IS CONFIDENTIAL AND IS DISCLOSED TO YOU ON CONDITION THAT NO FURTHER DISCLOSURE IS MADE BY YOU TO OTHER THAN TOP-LINK PERSONNEL WITHOUT WRITTEN AUTHORIZATION FROM TOP-LINK LTD.

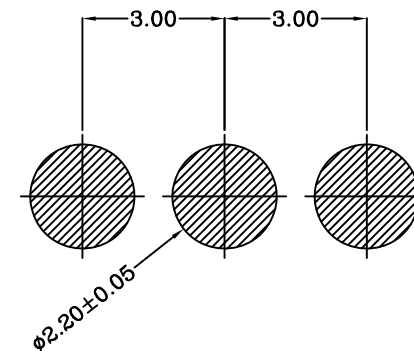
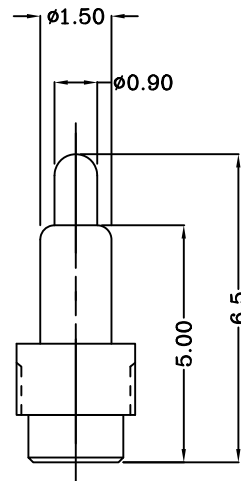
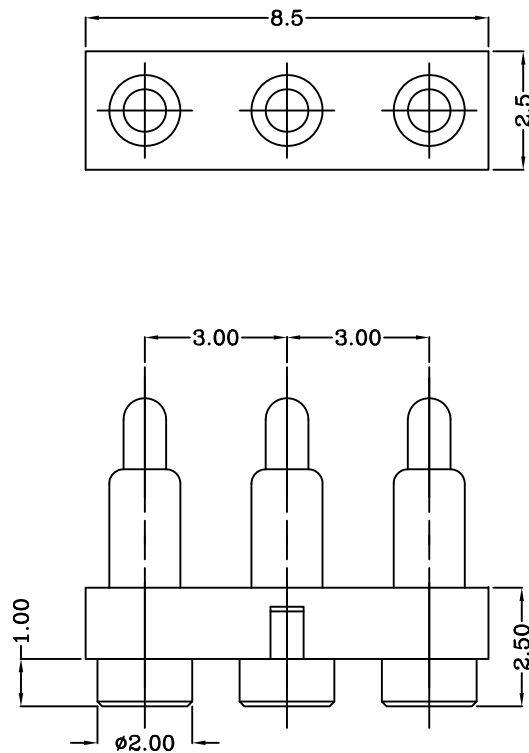
DWG NO.

C-110227



USED ON

—






Recommended PCB Layout  
Recommended solder paste thickness is 0.10 mm

Notes:

- Material, Housing: PA 4.6 (30% Glass Filled)  
Color Black.  
Contact: Brass
- Mechanical demands:  
Plating Plunger: 0.4um Au over 1.4um Ni  
Plating Body: 0.1um Au over 1.4um Ni.

110227-3

PART NUMBER

|   |  |    |                 |                     |  |                 |          |
|---|--|----|-----------------|---------------------|--|-----------------|----------|
| DIMENSIONS IN MM<br>TOLERANCES UNLESS<br>OTHER SPECIFIED<br>0 = ±-<br>0.0 = ±0.15<br>0.00 = ±0.10<br>0.000 = ±<br>ANGLE: ±1°<br><br>SURF TEXTURE: 3.2/▽<br><br>REMOVE BURRS. BREAK<br>SHARP EDGES R0.05 MAX<br>DO NOT SCALE PRINT | MATL  |    | HT TR —         |                     | FIN —                         |                 |          |
|   | DWN<br>Benny   |    | APVD<br>Lansing |                     |  Top-Link<br>Electronics Ltd. |                 |          |
|   | CHK<br>Andy  |    | REL             |                     |  |                 |          |
|   | NAME   |    |                 |                     |  |                 |          |
|   | PGO 3P<br>PGC-1.5-6.5-R-3P-3.0PH   |    |                 |                     |  |                 |          |
| SCALE<br>1:1  |  | A4 |                 | DWG<br>NO. C-110227 |  | SHEET<br>1 OF 1 | REV<br>B |

|      |   |
|------|---|
| LDC  | - |
| DIST | - |

|               |                 |            |      |
|---------------|-----------------|------------|------|
| update remark |                 | R007/18/E1 |      |
| LTR           | REVISION RECORD | APVD       | DATE |

4

3

2

1